

ENGINEERING DEPT.		PRODUCT SPECIFICATION For High Density Straight Dip D-Sub Connector of System CD04	SPEC.NO.: SPCD026C
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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: **CD04 Series**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

1.6 mm (.063")

REVIEWED : Eisley APPROVED : Sun VERIFIED : Michelle .



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7. ELECTRICAL PERFORMANCE:

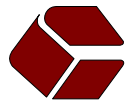
	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 5000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact retaining force in insulator	Retention speed 25± 3 mm per minute from housing	More than 4.0 Kgf
8.2	Single contact insertion force	Measure force to insertion using Ø 0.78 mm test pin at speed 25± 3 mm per minute	240 gram max.
8.3	Single contact withdrawal force	Measure force to withdrawal using Ø 0.74 mm test pin at speed 25± 3 mm per minute	15 gram min.
8.4	Durability	Connector shall be subjected to 100 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Solder ability	Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5°C Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area



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	ITEM	TEST CONDITION	REQUIREMENT
9.4	Resistance to soldering heat	<p>Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: $240 \pm 5^{\circ}\text{C}$</p> <p>Lead-Free Process Soldering time: 5 ± 0.5 second Soldering pot: $260 \pm 5^{\circ}\text{C}$</p>	No damage
9.5	Heat aging	$105 \pm 2^{\circ}\text{C}$, 96 hours	No damage
9.6	Humidity	$40 \pm 2^{\circ}\text{C}$, 90-95% RH , 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.7	Temperature cycling	One cycle consists of : (1) $-55^{+0}_{-3}^{\circ}\text{C}$, 30 min. (2) Room temp. 10-15 min. (3) $85^{+3}_{-0}^{\circ}\text{C}$, 30 min. (4) Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.8	Salt spray	<p>Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated)</p> <p>Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed.</p> <p>The specimens shall be suspended from the top using waxed twine, string or nylon thread.</p> <p>The test only define the plating area, without plating area (as copper cross section) will not be defined.</p> <p>(EIA 364-26B / MIL-STD-202 Method 101)</p>	Appearance: No damage Contact resistance: Less than twice of initial



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10. AMBIENT TEMPERATURE RANGE: -40 to + 105°C

11. MATING FORCE AND UNMATING FORCE:

Unit: Kgf

No. of Circuits	Mating Force (Initial max.)	Unmating Force (Initial max.)
15	5.1	3.8
26	9.2	6.9
44	12.6	8.6
62	16.4	10.8

CviLux